- Compatible With PC 99 Desktop Line-Out Into 10-kΩ Load
- Compatible With PC 99 Portable Into 8-Ω
 Load
- Internal Gain Control, Which Eliminates External Gain-Setting Resistors
- Digital Volume Control From 20 dB to –40 dB
- 2-W/Ch Output Power Into 3-Ω Load
- PC-Beep Input
- Depop Circuitry
- Stereo Input MUX
- Fully Differential Input
- Low Supply Current and Shutdown Current
- Surface-Mount Power Packaging 24-Pin TSSOP PowerPAD™

(TOP VIEW) GND □ 10 24 ☐ GND UP \Box 2 23 ☐ RLINEIN DOWN I 3 22 **SHUTDOWN** 21 LOUT+ □□ 4 ☐ ROUT+ LLINEIN I 5 20 □ RHPIN LHPIN \square 6 19 \square V_{DD} 18 7 □ PV_{DD} PV_{DD} \square RIN 🗆 8 17 ☐ CLK LOUT- I 9 16 ☐ ROUT-☐ SE/BTL LIN \Box 10 15 14 BYPASS □□ PC-BEEP 11 GND □ 13 □ GND 12

PWP PACKAGE

description

The TPA0162 is a stereo audio power amplifier in a 24-pin TSSOP thermally enhanced package capable of delivering 2 W of continuous RMS power per channel into $3-\Omega$ loads. This device minimizes the number of external components needed, which simplifies the design and frees up board space for other features. When driving 1 W into $8-\Omega$ speakers, the TPA0162 has less than 0.22% THD+N across its specified frequency range.

Included within this device is integrated depop circuitry that virtually eliminates transients that cause noise in the speakers.

Amplifier gain is controlled by two terminals, $\overline{\text{UP}}$ and $\overline{\text{DOWN}}$. There are 31 discrete steps covering the range of 20 dB (maximum volume setting) to –40 dB (minimum volume setting) in 2 dB steps. By pressing either button momentarily, the volume steps up or down 2 dB. By continuing to hold the button down, the device will start stepping through volume settings at a rate determined by the capacitor on the CLK terminal. An internal input MUX allows two sets of stereo inputs to the amplifier. In notebook applications, where internal speakers are driven as BTL and the line outputs (often headphone drive) are required to be SE, the TPA0162 automatically switches into SE mode when the SE/BTL input is activated. This effectively reduces the gain by 6 dB.

The TPA0162 consumes only 20 mA of supply current during normal operation. A miserly shutdown mode is included that reduces the supply current to less than 150 μA.

The PowerPAD package (PWP) delivers a level of thermal performance that was previously achievable only in TO-220-type packages. Thermal impedances of approximately 35°C/W are truly realized in multilayer PCB applications. This allows the TPA0162 to operate at full power into $8-\Omega$ loads at ambient temperatures of 85° C.

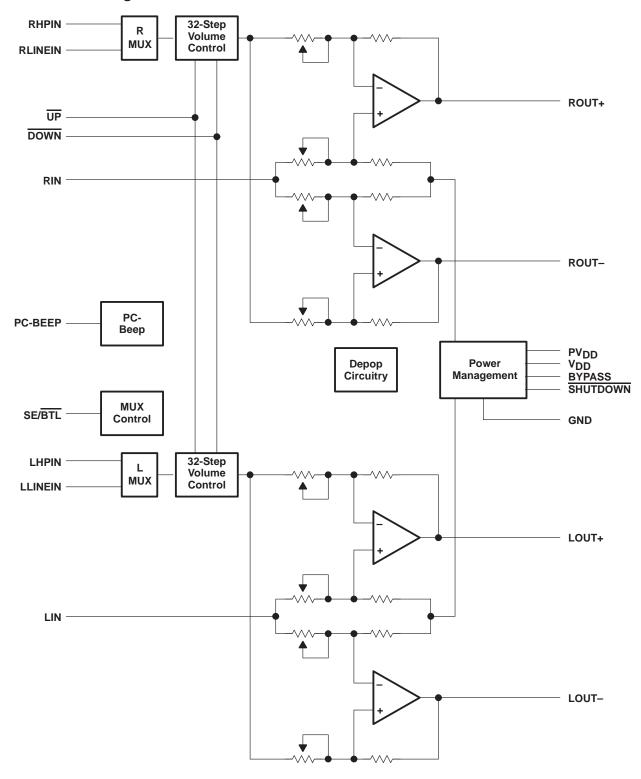


Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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functional block diagram





AVAILABLE OPTIONS

	PACKAGED DEVICE		
TA	TSSOP† (PWP)		
−40°C to 85°C	TPA0162PWP		

[†] The PWP package is available taped and reeled. To order a taped and reeled part, add the suffix R to the part number (e.g., TPA0162PWPR).

Terminal Functions

TERMINAL						
NAME	NO.	I/O	DESCRIPTION			
BYPASS	11		Tap to voltage divider for internal mid-supply bias generator			
CLK	17	I	If a 47-nF capacitor is attached, the TPA0162 generates an internal clock. An external clock can override the internal clock input to this terminal.			
DOWN	3	I	A momentary pulse on this terminal decreases the volume level by 2 dB. Holding the terminal low for a period of time will step the amplifier through the volume levels at a rate determined by the capacitor on the CLK terminal.			
GND	1, 12 13, 24		Ground connection for circuitry. Connected to thermal pad			
LHPIN	6	I	Left-channel headphone input, selected when SE/BTL is held high			
LIN	10	I	Common left input for fully differential input. AC ground for single-ended inputs			
LLINEIN	5	I	Left-channel line negative input, selected when SE/BTL is held low			
LOUT+	4	0	Left-channel positive output in BTL mode and positive in SE mode			
LOUT-	9	0	Left-channel negative output in BTL mode and high impedance in SE mode			
PC-BEEP	14	I	The input for PC Beep mode. PC-BEEP is enabled when a > 1-V (peak-to-peak) square wave is input to PC-BEEP or PCB ENABLE is high.			
PV _{DD}	7, 18	I	Power supply for output stage			
RHPIN	20	ı	Right channel headphone input, selected when SE/BTL is held high			
RIN	8	I	Common right input for fully differential input. AC ground for single-ended inputs			
RLINEIN	23	I	Right-channel line input, selected when SE/BTL is held low.			
ROUT+	21	0	Right-channel positive output in BTL mode and positive in SE mode			
ROUT-	16	0	Right-channel negative output in BTL mode and high impedance in SE mode			
SE/BTL	15	ı	Input MUX control input. When this terminal is held high, the LHPIN or RHPIN and SE output is selected. When this terminal is held low, the LLINEIN or RLINEIN and BTL output are selected.			
SHUTDOWN	22	I	When held low, this terminal places the entire device, except PC-BEEP detect circuitry, in shutdown mode.			
UP	2	I	A momentary pulse on this terminal increases the volume level by 2 dB. Holding the terminal low for a period of time will step the amplifier through the volume levels at a rate determined by the capacitor on the CLK terminal.			
V_{DD}	19	I	Analog V _{DD} input supply. This terminal needs to be isolated from PV _{DD} to achieve highest performance.			

TPA0162 STEREO 2-W AUDIO POWER AMPLIFIER WITH DIGITAL VOLUME CONTROL

SLOS249A - JUNE 1999 - REVISED JUNE 1999

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{DD}	6 V
Input voltage, V _I	0.3 V to V _{DD} +0.3 V
Continuous total power dissipation	internally limited (see Dissipation Rating Table)
Operating free-air temperature range, T _A	40°C to 85°C
Operating junction temperature range, T _J	40°C to 150°C
Storage temperature range, T _{stq}	
Lead temperature 1.6 mm (1/16 inch) from case for 10 seco	nds 260°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

DISSIPATION RATING TABLE

PACKAGE	$T_{\mbox{A}} \le 25^{\circ}\mbox{C}$	DERATING FACTOR	T _A = 70°C	T _A = 85°C
PWP	2.7 W‡	21.8 mW/°C	1.7 W	1.4 W

[‡] Please see the Texas Instruments document, *PowerPAD Thermally Enhanced Package Application Report* (literature number SLMA002), for more information on the PowerPAD package. The thermal data was measured on a PCB layout based on the information in the section entitled *Texas Instruments Recommended Board for PowerPAD* on page 33 of the before mentioned document.

recommended operating conditions

		MII	MAX	UNIT
Supply voltage, V _{DD}		4.	5 5.5	V
High level input voltage. V	SE/BTL		4	٧
High-level input voltage, V _{IH}	SHUTDOWN		2	
Low level input valtage Viv	SE/BTL		3	.,
Low-level input voltage, V _{IL}	SHUTDOWN		0.8	1 °
Operating free-air temperature, T _A		-4) 85	°C



electrical characteristics at specified free-air temperature, V_{DD} = 5 V, T_A = 25°C (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
IVODI	Differential output voltage				25	mV	
PSRR	Power supply rejection ratio	$V_{DD} = 4.9 \text{ V to } 5.1 \text{ V}$		67		dB	
ШН	High-level input current	$V_{DD} = 5.5 \text{ V},$ $V_{I} = V_{DD}$			900	nA	
IIILI	Low-level input current	V _{DD} = 5.5 V, V _I = 0 V			900	nA	
IDD	Supply current	BTL mode		20		mA	
		SE mode		10		IIIA	
I _{DD(sd)}	Supply current, shutdown mode			150	300	μΑ	

operating characteristics, V_{DD} = 5 V, T_A = 25°C, R_L = 4 Ω , Gain = 2 V/V, BTL mode (unless otherwise noted)

	PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
PO	Output power	THD = 1%,	f = 1 kHz		2		W
THD + N	Total harmonic distortion plus noise	P _O = 1 W,	f = 20 Hz to 15 kHz		0.22%		
ВОМ	Maximum output power bandwidth	THD = 5%			>15		kHz
kaa	Supply ripple rejection ratio	f = 1 kHz, C _B = 0.47 μF	BTL mode		65		dB
^k SVR			SE mode		60		
Vn	Noise output voltage	$C_B = 0.47 \mu\text{F},$ f = 20 Hz to 20 kHz	BTL mode		17		μVRMS
			SE mode		44		

APPLICATION INFORMATION

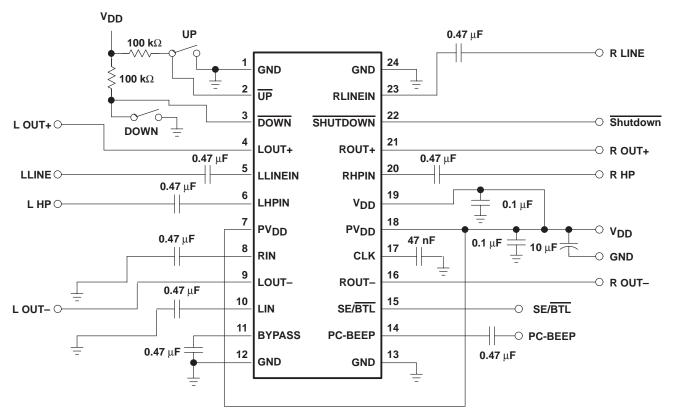


Figure 1. Typical TPA0162 Application Circuit

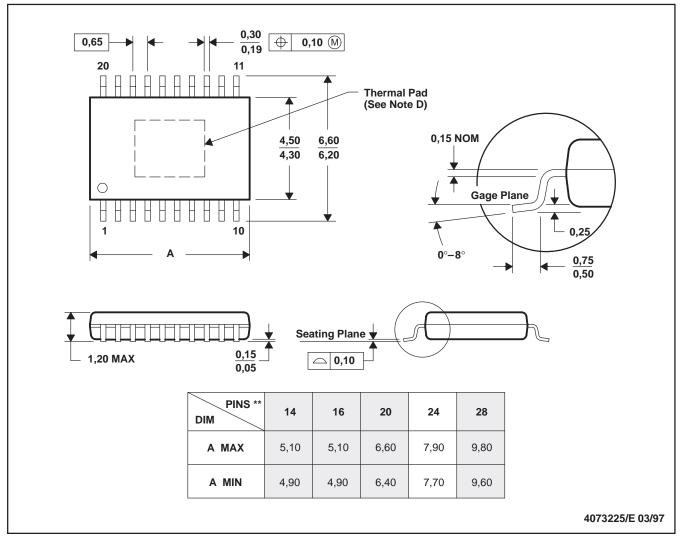


MECHANICAL DATA

PWP (R-PDSO-G**)

PowerPAD™ PLASTIC SMALL-OUTLINE PACKAGE

20-PIN SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusions.
 - D. The package thermal performance may be enhanced by bonding the thermal pad to an external thermal plane. This pad is electrically and thermally connected to the backside of the die and possibly selected leads.
 - E. Falls within JEDEC MO-153

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